Artem Kulakevich

Education

Sep 2017 | BS in Electrical Engineering, Portland State University, GPA: 3.97, Portland, OR. Jun 2020

Jun 2019 | MS in Digital IC Design, Test, and Validation, Portland State University, GPA: 4.0, Jun 2022 Portland, OR.

Work Experience

Apr 2017 - Production Specialist III, Micro Systems Engineering Inc., Lake Oswego, OR.

- Present Certified for and operate more production processes than the majority of other employees.
 - Rebuilt and taught multiple automated imaging cells used in production for thousands of modules daily. Maintained and updated the imaging cell for new product types and configuration changes.

Skills

Software SystemVerilog, Arm Assembly, LabView, C, C++, Matlab

Hardware Soldering, Electrical Wiring, Oscilloscope, DMM

General Excel, Word, PowerPoint, LTSpice, Jira, SAP BusinessObjects

Projects

Module Imaging Cell, Lab View, Epson RC+, Soldering, Crimping.

Rebuilt multiple 4-Axis robots based on BOM, retaught robots for production, created documentation for teaching robots in the future. Continue to maintain robots and make improvements.

Blur Detection and Image Matching, Lab View NI Vision.

Created a VI that does image matching based on a template, converts a bounding box to an ROI, and then uses the ROI to find a blur average value that is then stored for use in a config file.

ASIC Design, System Verilog, Design Compiler, Git, Linux.

Programmed multiple Verilog designs including FIFO, counters, and traffic lights. Synthesized the projects for comparison with simulation.

ARM Sitara AM335x UART / I2C, ARM Assembly, C.

Programmed BeagleBone Black boards to communicate with a RC8660 talker boards and NewHaven LCD using barebone assembly.

Buck Converter, Oscilloscope, Matlab, Soldering.

Built buck converter design, tested the design, and then improved the design by changing the compensator stage using bode plot analysis.

Fixture Build, Soldering.

Built multiple fixture based on BOM and schematics used in testing production pacemakers and defibrillator. Completed probe alignment/compression testing, soldering, verification, and release.